



US00D923158S

(12) **United States Design Patent** (10) **Patent No.:** **US D923,158 S**
Kang et al. (45) **Date of Patent:** **** Jun. 22, 2021**

(54) **SEAL MEMBERS FOR USE IN
SEMICONDUCTOR PRODUCTION
APPARATUS**

CPC F16K 51/02; F16J 15/025; F16J 15/0887;
F16J 15/104; F16J 15/128
See application file for complete search history.

(71) Applicant: **Valqua, Ltd.**, Tokyo (JP)

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Yoshida**, Nara (JP)

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(73) Assignee: **Valqua, Ltd.**, Tokyo (JP)

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(**) Term: **15 Years**

(Continued)

(21) Appl. No.: **29/714,184**

(22) Filed: **Nov. 21, 2019**

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Related U.S. Application Data

(62) Division of application No. 35/506,053, filed on May 14, 2018 (U.S. filing date under 35 U.S.C. 384), and having an international filing date of May 14, 2018, now Pat. No. Des. 897,504.

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(30) **Foreign Application Priority Data**

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Nov. 17, 2017	(JP)	2017-025722

(57) **CLAIM**

The ornamental design for a seal member for use in semiconductor production apparatus, as shown and described.

(51) **LOC (13) Cl.** **23-01**

(52) **U.S. Cl.**
USPC **D23/269**
CPC **F16J 15/025** (2013.01)

DESCRIPTION

(58) **Field of Classification Search**

USPC D15/7, 9, 11, 17, 21, 28, 123, 199;
D23/269, 386, 259; D8/349;
277/602–626; 285/95, 109, 336, 910, 918

FIG. 1 is a perspective view of a seal member for use in semiconductor production apparatus, showing our new design;

FIG. 2 is a front elevation view thereof;

FIG. 3 is a rear elevation view thereof;

FIG. 4 is a left side elevation view thereof;

FIG. 5 is a right side elevation view thereof;

FIG. 6 is a top view thereof;

FIG. 7 is a bottom view thereof;

FIG. 8 is a cross-sectional view thereof; and,

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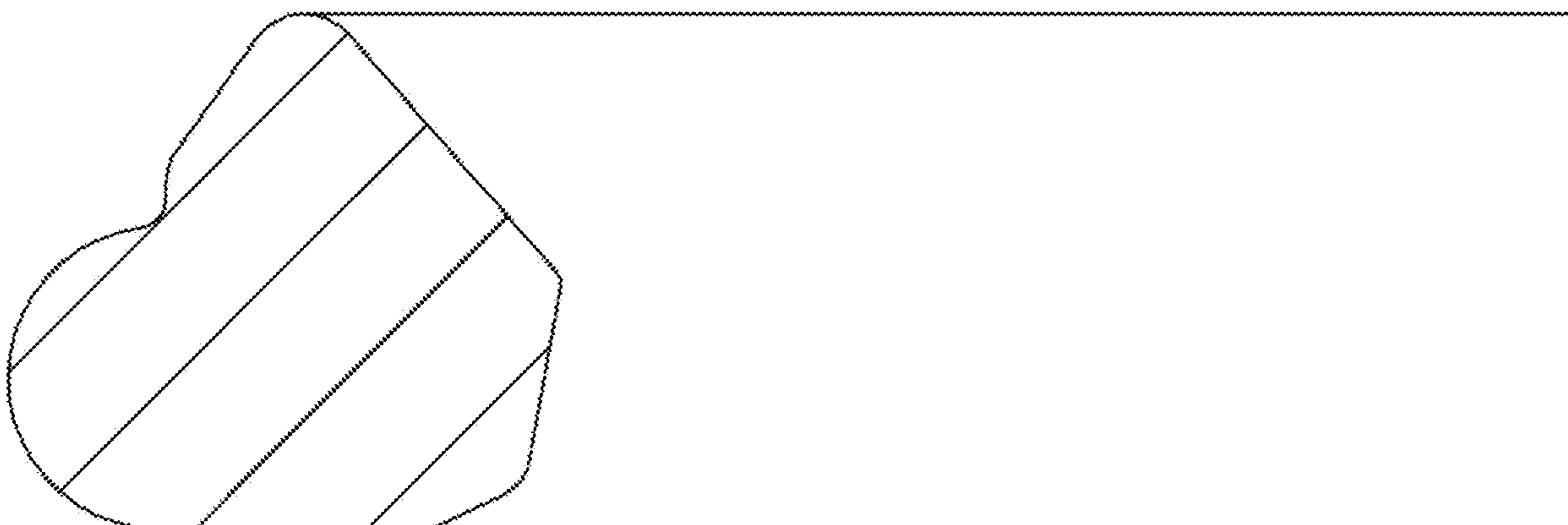


FIG. 9 is an enlarged cross-sectional view of a portion thereof.

1 Claim, 9 Drawing Sheets

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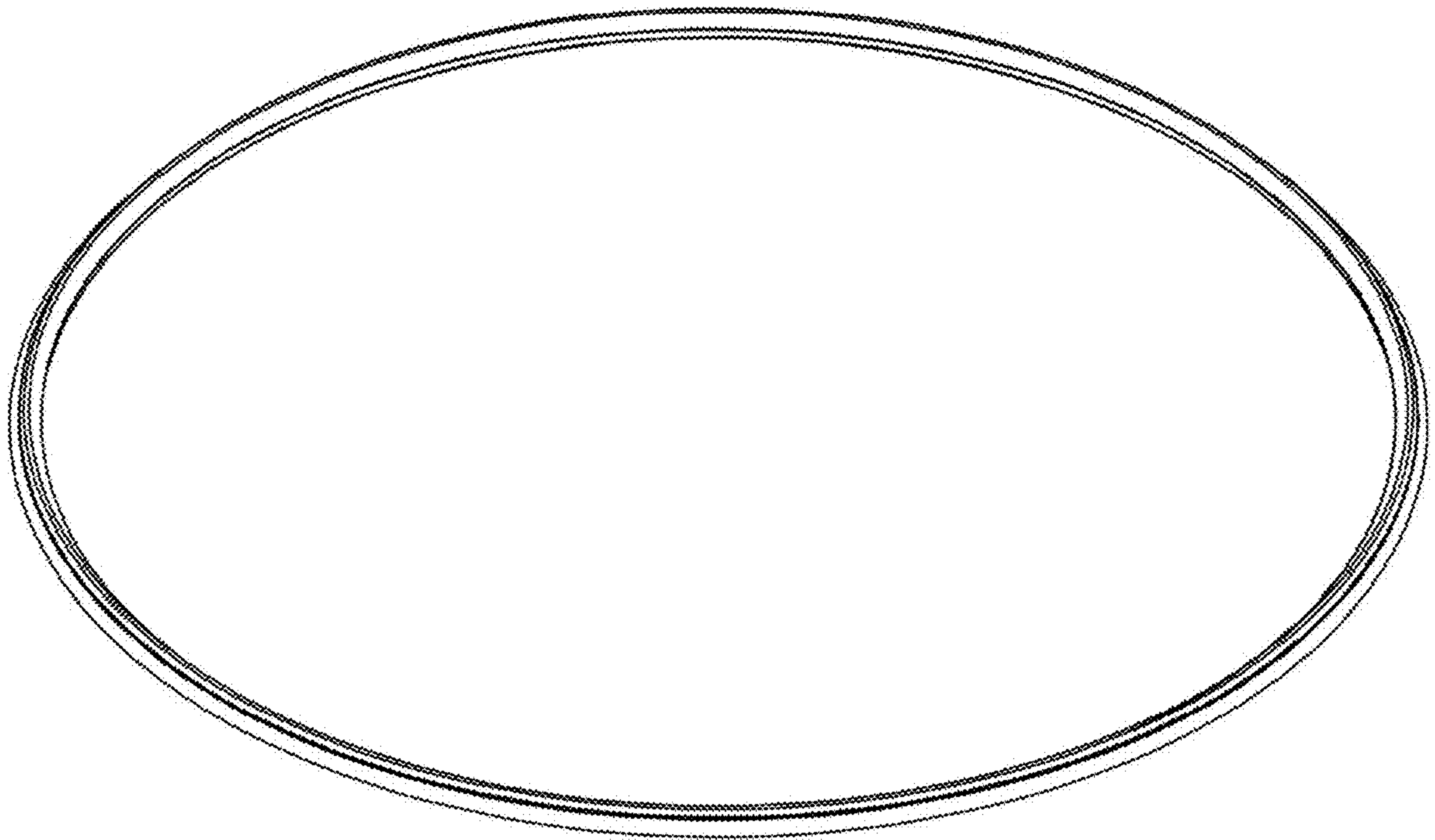


FIG. 1



FIG. 2



FIG. 3

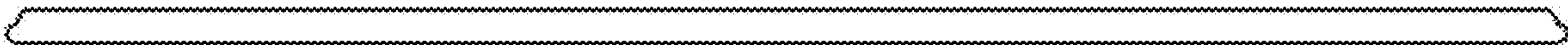


FIG. 4

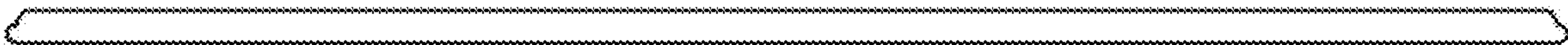


FIG. 5

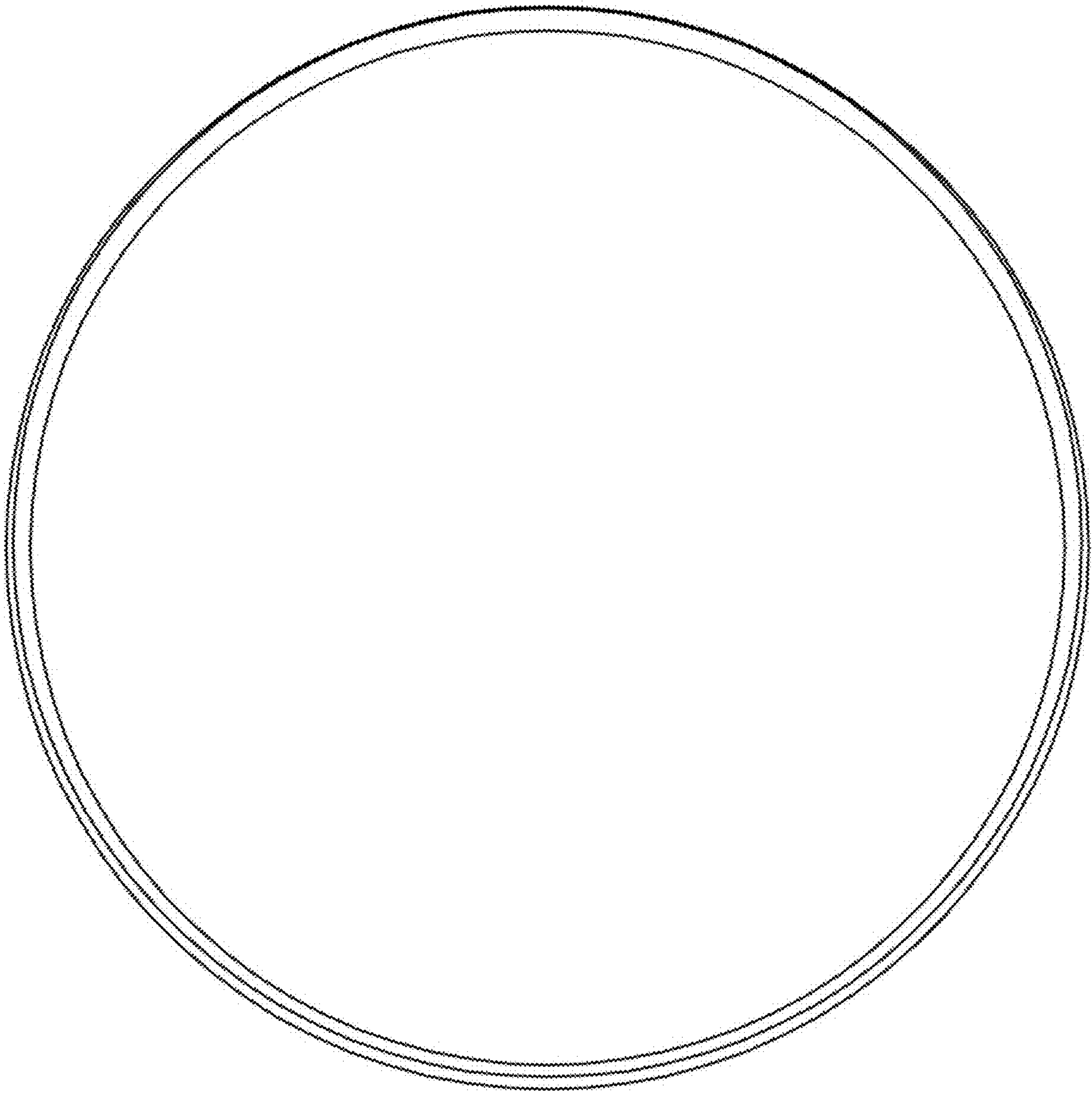


FIG. 6

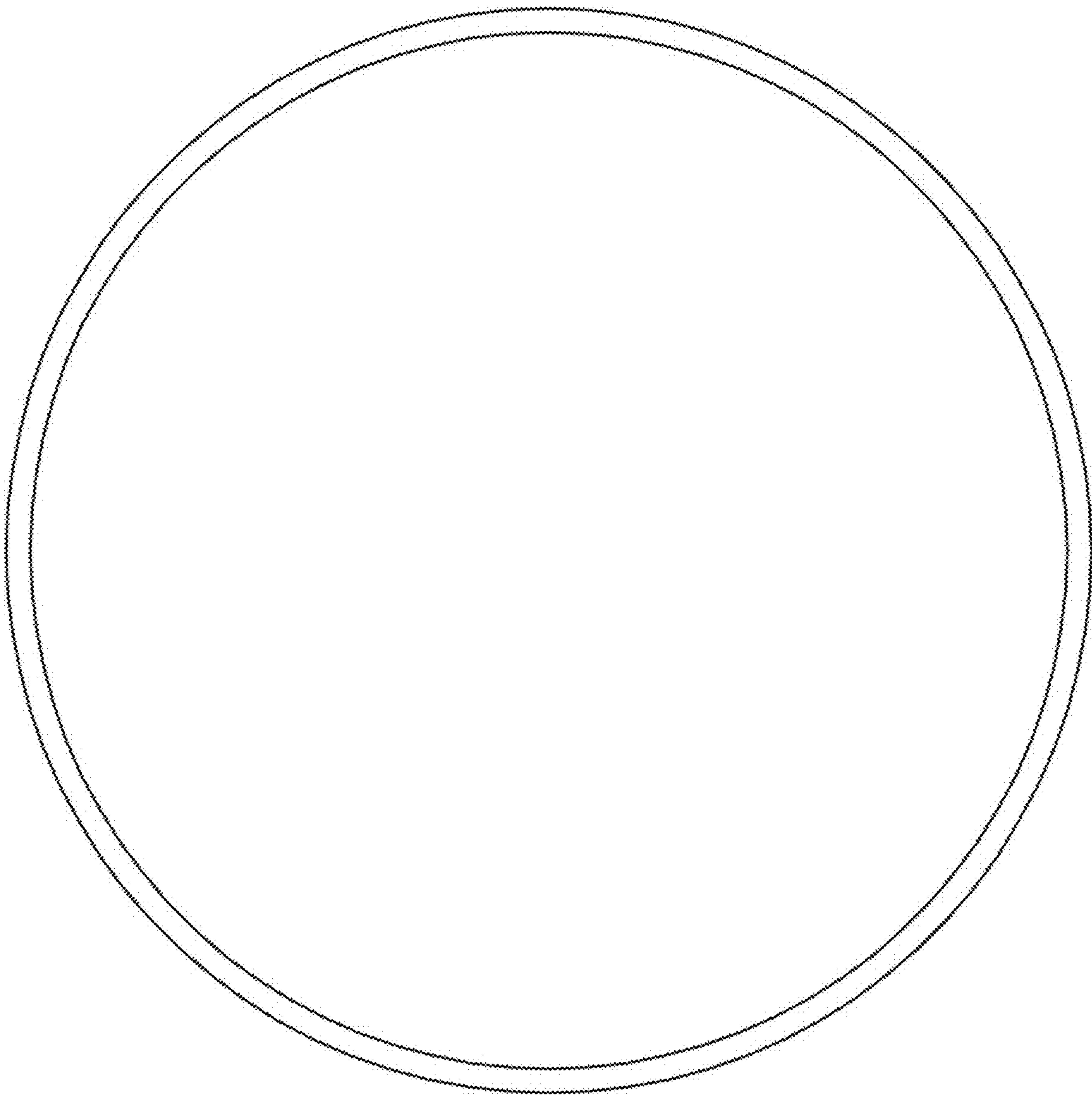


FIG. 7



FIG. 8

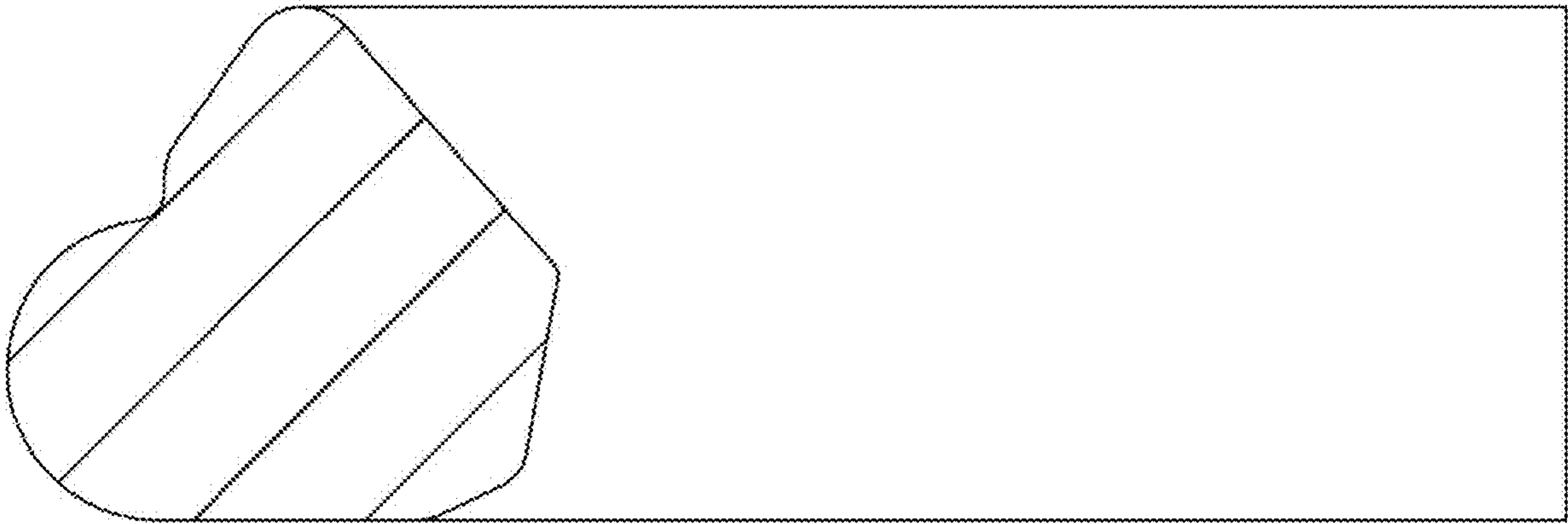


FIG. 9